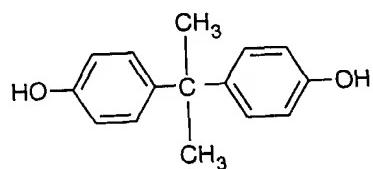


REMARKS/ARGUMENTS

Responsive to the restriction requirement set forth in the Official Action of May 29, 2003, Applicant elects Group II, claims 26-37, drawn to an epoxy resin composition wherein the content of an organic filler (c) is from 60-95% by wt. Group II includes the species of I, II, and V. Applicants elect Species V (claim 37), Examples 18-20 in the specification.

As to the objection as noted on page 5 of the Official Action, claim 38 is amended to depend from claim 26. In addition, new claims 44 and 45 are added that are similar to claim 38 but dependent from claims 30 and 34 respectively. New claims 38, 44 and 45 should be examined with the elected Group II.

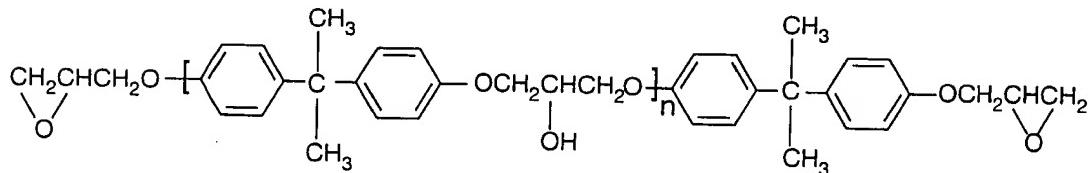
The structure of "bisphenol A" is that of 2,2'-bis(p-hydroxyphenyl)propane:



Therefore, the term "bisphenol A type epoxy resin" means an epoxy resin having the structure of "bisphenol A" as its skeleton for epoxidization.

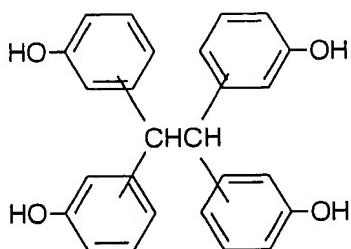
Furthermore, the term "type" used to categorize epoxy resin having the basal structure of a pheolic skeleton for epoxidization, such as "bisphenol A type epoxy resin", are very often utilized in this technical field. See column 4, lines 15-38 of US patent No. 6,054,222, or column 2, lines 40-48 of U.S. patent No. 5,854,316, both the two references were cited in the previous Official Action.

Thus, there is a widely accepted consensus that a Bisphenol A type epoxy resin commonly has a generic formula:



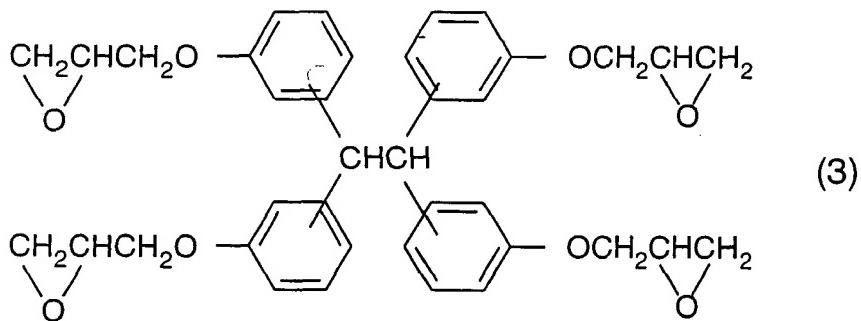
wherein n is 0 or any integer. In this view, the term "bisphenol A type epoxy resin" is commonly understood to denote concisely the formulae shown above.

The structure of "tetraphenylolethane" is that of 1,1,2,2-tetra(hydroxyphenyl)ethane:



Therefore, the term "tetraphenylolethane type epoxy resin" or "epoxy resin of tetraphenylolethane type" means an epoxy resin having the structure of "tetraphenylolethane" as its skeleton for epoxidization.

Ideally, fully epoxidized "tetraphenylolethane" has four epoxy groups as represented by structure of formula (3):



However, in actuality, some portion of epoxidized "tetraphenylolethane" products has only three epoxy groups, as their epoxidation is not completely furnished. Thus, an actual "tetraphenylolethane type epoxy resin" obtained is usually a mixture of the resin having four epoxy groups and the resin having three epoxy groups with one hydroxy unreacted. In this view, such a phrase as "a tetraphenylolethane type epoxy resin to which three or four

epoxy groups are bonded" may be understood to be more reasonable for denoting the actual "tetraphenylolethane type epoxy resin" obtained.

Further, the positions of radical bond for hydroxyphenyl group are three type; o-, m- and p-positions. Therefore, there are two or more isomers for "tetraphenylolethane type epoxy resin" having exactly four epoxy groups.

The amendment to claims 26 and 34 is believed to address the objection on page 5, paragraph 2 of the Official Action.

When $W = 60$, the relation of $0.30W - 13 \leq E \leq 3.7W - 184$ gives $0.30 \times 60 - 13 \leq E \leq 3.7 \times 60 - 184$ that is $5.0 \leq E \leq 38.0$.

When $W = 60$, the relation of $0.015W + 4.1 \leq E \leq 0.27W + 21.8$ gives also $0.015 \times 60 + 4.1 \leq E \leq 0.27 \times 60 + 21.8$ that is $5.0 \leq E \leq 38.0$.

In this case, the combination of the relation of $0.015W + 4.1 \leq E \leq 0.27W + 21.8$ in this case of $30 \leq W < 60$ with the relation of $0.30W - 13 \leq E \leq 3.7W - 184$ for the case of $W=60$ leads to the same conception to the relation

of $0.015W + 4.1 \leq E \leq 0.27W + 21.8$ for the case of $30 \leq W < 60$ and $W=60$.

The specification has good support for the specific case of $W=60$ as explained above, so that the combination of the relation of $0.015W + 4.1 \leq E \leq 0.27W + 21.8$ in the case of $30 \leq W < 60$ with the relation of $0.30W - 13 \leq E \leq 3.7W - 184$ for the case of $W=60$ is clearly supported by the disclosure of the specification and drawing of Fig. 1.

When assumed the compositions of Example 1 and Example 2 listed in Table 1, the relative ratio of each component for the resin components other than the inorganic filler of Example 1 is substantially the same to the relative ratio of each component for the resin components other than the inorganic filler of Example 2. Thus, the compositions of Example 1 and Example 2 are different only in the ratio to the weight of the inorganic filler versus total weight of the resin components other than the inorganic filler.

It means that the compositions of Example 2 is obtainable by adding the inorganic filler to the

compositions of Example 1 to adjust the content of inorganic filler from 60.0 wt% up to 70.5 wt%.

As explained above, if the relative ratio of each component for the resin components other than the inorganic filler is the same for two compositions having only a difference in the ratio to the weight of the inorganic filler versus total weight of the resin components other than the inorganic filler, the composition with higher content of the inorganic filler can be defined in the similar manner by using the composition with lower content of the inorganic filler as a composition reference.

Claims 39 to 43 are all defined by the way mentioned above. In this view, such style for defining the composition composed of the inorganic filler (solid component) and the remaining fluid mixture of the resin components other than the inorganic filler seems to be well supported by description of the specification.

A favorable action on the merits is respectfully requested.

The Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment or credit any overpayment to Deposit Account No. 25-0120 for any

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additional fees required under 37 C.F.R. § 1.16 or under 37
C.F.R. § 1.17.

Respectfully submitted,

YOUNG & THOMPSON



Liam McDowell, Reg. No. 44,231
Attorney for Applicants
745 South 23rd Street
Arlington, VA 22202
Telephone (703) 521-2297

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